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What Are <u>Embedded - Microcontrollers - Application Specific</u>?

Application charific microcontrollars are angineered to

Details	
Product Status	Obsolete
Applications	Capacitive Sensing
Core Processor	M8C
Program Memory Type	FLASH (8kB)
Controller Series	CY8C20xx6
RAM Size	1K x 8
Interface	I ² C, SPI
Number of I/O	20
Voltage - Supply	1.71V ~ 5.5V
Operating Temperature	-40°C ~ 85°C
Mounting Type	Surface Mount
Package / Case	24-UFQFN Exposed Pad
Supplier Device Package	24-QFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c20336-24lqxi

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Additional System Resources

System Resources, some of which are listed in the previous sections, provide additional capability useful to complete systems. Additional resources include low voltage detection and power on reset. The merits of each system resource are listed here:

- The I2C slave/SPI master-slave module provides 50/100/400 kHz communication over two wires. SPI communication over three or four wires runs at speeds of 46.9 kHz to 3 MHz (lower for a slower system clock).
- The I2C hardware address recognition feature reduces the already low power consumption by eliminating the need for CPU intervention until a packet addressed to the target device is received.
- Low Voltage Detection (LVD) interrupts can signal the application of falling voltage levels, while the advanced POR (Power-On-Reset) circuit eliminates the need for a system supervisor.
- An internal reference provides an absolute reference for capacitive sensing.
- A register-controlled bypass mode allows the user to disable the LDO.
- Standard Cypress PSoC IDE tools are available for debugging the CY8C20x36/46/66/96 family of parts. However, the additional trace length and a minimal ground plane in the Flex-Pod can create noise problems that make it difficult to debug the design. A custom bonded On-Chip Debug (OCD) device is available in an 48-pin QFN package. The OCD device is recommended for debugging designs that have high current and/or high analog accuracy requirements. The QFN package is compact and is connected to the ICE through a high density connector.

Getting Started

The quickest way to understand PSoC silicon is to read this data sheet and then use the PSoC Designer Integrated Development Environment (IDE). This data sheet is an overview of the PSoC integrated circuit and presents specific pin, register, and electrical specifications.

For in depth information, along with detailed programming details, see the PSoC® Programmable System-on-Chip Technical Reference Manual for CY8C20x36/46/66/96 PSoC Devices.

For up-to-date ordering, packaging, and electrical specification information, see the latest PSoC device data sheets on the web at www.cypress.com/psoc.

Application Notes

Application notes are an excellent introduction to the wide variety of possible PSoC designs. They are located here: www.cypress.com/psoc. Select Application Notes under the Documentation tab.

Development Kits

PSoC Development Kits are available online from Cypress at www.cypress.com/shop and through a growing number of regional and global distributors, which include Arrow, Avnet, Digi-Key, Farnell, Future Electronics, and Newark.

Training

Free PSoC technical training (on demand, webinars, and workshops) is available online at www.cypress.com/training. The training covers a wide variety of topics and skill levels to assist you in your designs.

CYPros Consultants

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Development Tools

PSoC Designer is a Microsoft® Windows-based, integrated development environment for the Programmable System-on-Chip (PSoC) devices. The PSoC Designer IDE and application runs on Windows XP and Windows Vista.

This system provides design database management by project, an integrated debugger with In-Circuit Emulator, in-system programming support, and built-in support for third-party assemblers and C compilers.

PSoC Designer also supports C language compilers developed specifically for the devices in the PSoC family.

PSoC Designer Software Subsystems

System-Level View

The system-level view is a drag-and-drop visual embedded system design environment based on PSoC Express. In this view you solve design problems the same way you might think about the system. Select input and output devices based upon system requirements. Add a communication interface and define the interface to the system (registers). Define when and how an output device changes state based upon any/all other system devices. Based upon the design, PSoC Designer automatically selects one or more PSoC devices that match your system requirements.

PSoC Designer generates all embedded code, then compiles and links it into a programming file for a specific PSoC device.

Chip-Level View

The chip-level view is a more traditional integrated development environment (IDE) based on PSoC Designer 4.x. You choose a base device to work with and then select different onboard analog and digital components called user modules that use the PSoC blocks. Examples of user modules are ADCs, DACs, Amplifiers, and Filters. You configure the user modules for your chosen application and connect them to each other and to the proper pins. Then you generate your project. This prepopulates your project with APIs and libraries that you can use to program your application.

The tool also supports easy development of multiple configurations and dynamic reconfiguration. Dynamic reconfiguration allows for changing configurations at run time.

Hybrid Designs

You can begin in the system-level view, allow it to choose and configure your user modules, routing, and generate code, then switch to the chip-level view to gain complete control over onchip resources. All views of the project share common code editor, builder, and common debug, emulation, and programming tools.

Code Generation Tools

PSoC Designer supports multiple third-party C compilers and assemblers. The code generation tools work seamlessly within the PSoC Designer interface and have been tested with a full range of debugging tools. The choice is yours.

Assemblers. The assemblers allow assembly code to be merged seamlessly with C code. Link libraries automatically use absolute addressing or are compiled in relative mode, and linked with other software modules to get absolute addressing.

C Language Compilers. C language compilers are available that support the PSoC family of devices. The products allow you to create complete C programs for the PSoC family devices.

The optimizing C compilers provide all the features of C tailored to the PSoC architecture. They come complete with embedded libraries providing port and bus operations, standard keypad and display support, and extended math functionality.

Debugger

PSoC Designer has a debug environment that provides hardware in-circuit emulation, allowing you to test the program in a physical system while providing an internal view of the PSoC device. Debugger commands allow the designer to read and program and read and write data memory, read and write I/O registers, read and write CPU registers, set and clear breakpoints, and provide program run, halt, and step control. The debugger also allows the designer to create a trace buffer of registers and memory locations of interest.

Online Help System

The online help system displays online, context-sensitive help for the user. Designed for procedural and quick reference, each functional subsystem has its own context-sensitive help. This system also provides tutorials and links to FAQs and an Online Support Forum to aid the designer in getting started.

In-Circuit Emulator

A low cost, high functionality In-Circuit Emulator (ICE) is available for development support. This hardware has the capability to program single devices.

The emulator consists of a base unit that connects to the PC by way of a USB port. The base unit is universal and operates with all PSoC devices. Emulation pods for each device family are available separately. The emulation pod takes the place of the PSoC device in the target board and performs full speed (24 MHz) operation.



Document Conventions

Acronyms Used

The following table lists the acronyms that are used in this document.

Table 1. Acronyms

Acronym	Description
AC	alternating current
API	application programming interface
CPU	central processing unit
DC	direct current
FSR	full scale range
GPIO	general purpose I/O
GUI	graphical user interface
ICE	in-circuit emulator
ILO	internal low speed oscillator
IMO	internal main oscillator
I/O	input/output
LSb	least-significant bit
LVD	low voltage detect
MSb	most-significant bit
POR	power on reset
PPOR	precision power on reset
PSoC®	Programmable System-on-Chip™
SLIMO	slow IMO
SRAM	static random access memory

Units of Measure

A units of measure table is located in the Electrical Specifications section. Table 11 on page 17 lists all the abbreviations used to measure the PSoC devices.

Numeric Naming

Hexadecimal numbers are represented with all letters in uppercase with an appended lowercase 'h' (for example, '14h' or '3Ah'). Hexadecimal numbers may also be represented by a '0x' prefix, the C coding convention. Binary numbers have an appended lowercase 'b' (for example, 01010100b' or '01000011b'). Numbers not indicated by an 'h', 'b', or 0x are decimal.

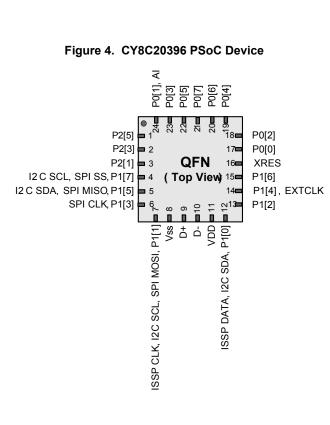


24-Pin QFN with USB

Table 4. Pin Definitions - CY8C20396 PSoC Device [2, 3]

Pin No.	Тур	ре	Nome	Description
PIII NO.	Digital	Analog	Name	Description
1	I/O	I	P2[5]	
2	I/O	I	P2[3]	
3	I/O	I	P2[1]	
4	IOHR	I	P1[7]	I2C SCL, SPI SS
5	IOHR	I	P1[5]	I2C SDA, SPI MISO
6	IOHR	I	P1[3]	SPI CLK
7	IOHR	I	P1[1]	ISSP CLK, I2C SCL, SPI MOSI
8	Pow	/er	VSS	Ground
9	I/O	I	D+	USB D+
10	I/O	I	D-	USB D-
11	Pow	ver	VDD	Supply
12	IOHR	I	P1[0]	ISSP DATA, I2C SDA
13	IOHR	I	P1[2]	
14	IOHR	I	P1[4]	Optional external clock input (EXTCLK)
15	IOHR	I	P1[6]	
16	RESET	INPUT	XRES	Active high external reset with internal pull down
17	IOH	I	P0[0]	
18	IOH	I	P0[2]	
19	IOH	I	P0[4]	
20	IOH	I	P0[6]	
21	IOH	I	P0[7]	
22	IOH	I	P0[5]	
23	IOH	I	P0[3]	Integrating input
24	IOH	I	P0[1]	Integrating input
СР	Pow	ver	VSS	Thermal pad must be connected to Ground

LEGEND I = Input, O = Output, OH = 5 mA High Output Drive, R = Regulated Output





32-Pin QFN (with USB)

Table 6. Pin Definitions - CY8C20496 PSoC Device [2, 3]

Pin	Ту	/pe	Mama	Description
No.	Digital	Analog	Name	Description
1	IOH	ı	P0[1]	
2	I/O	I	P2[5]	XTAL Out
3	I/O	I	P2[3]	XTAL In
4	I/O	I	P2[1]	
5	IOHR	I	P1[7]	I2C SCL, SPI SS
6	IOHR	I	P1[5]	I2C SDA, SPI MISO
7	IOHR	I	P1[3]	SPI CLK
8	IOHR	I	P1[1]	TC CLK, I2C SCL, SPI MOSI
9	Po	wer	V_{SS}	Ground Pin
10		!	D+	USB PHY
11		I	D-	USB PHY
12	Po	wer	Vdd	Power pin
13	IOHR	I	P1[0]	TC DATA*, I2C SDA, SPI CLKI
14	IOHR	I	P1[2]	
15	IOHR	I	P1[4]	EXTCLK
16	IOHR	I	P1[6]	
17	In	put	XRES	Active high external reset with internal pull down
18	I/O	I	P3[0]	
19	I/O	I	P3[2]	
20	I/O	I	P2[0]	
21	I/O	I	P2[2]	
22	I/O	I	P2[4]	
23	I/O	I	P2[6]	
24	IOH	I	P0[0]	
25	IOH	I	P0[2]	
26	IOH	I	P0[4]	
27	IOH	I	P0[6]	
28	Po	wer	Vdd	Power Pin
29	IOH	I	P0[7]	
30	IOH	I	P0[5]	
31	IOH	I	P0[3]	
32	Po	wer	Vss	Ground Pin

Figure 5. CY8C20496 PSoC Device Vss Po[3], Al Po[5], Al Po[7], Al Vdd Po[6], Al Po[4], Al AI, P0[1] P0[0], AI P2[6], AI P2[4], AI P2[2], AI P2[0], AI XTAL OUT, P2[5] 23= XTAL IN , P2[3] 22= AI, P2[1] **QFN** 21= I2C SCL, SPI SS, P1[7] 20₌ (Top View) I2C SDA, SPI MISO, P1[5] 19= P3[2], AI SPI CLK , P1[3] 7
TC CLK , I2C SCL , SPI MOSI, P1[1] 8 8 9 9 P3[0], AI 18= XRES VSS USB PHY, D+ USB PHY, D+ USB PHY D- USB P

 $\textbf{LEGEND} \quad \text{A = Analog, I = Input, O = Output, OH = 5 mA High Output Drive, R = Regulated Output.}$

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48-Pin SSOP

Table 7. Pin Definitions - CY8C20536, CY8C20546, and CY8C20566 PSoC Device $\ensuremath{^{[2]}}$

Pin No.	Digital	Analog	Name	Description	Figu	ıre 6.	CY8	C20536	, CY8C205	546, a	nd CY8C20566 PSoC Device
Pin	Dig	Ana	Hame	Bescription				AI, P0[7] 1		48 V DD
1	IOH		P0[7]						5] = 2 3] = 3		47 P0[6], AI 46 P0[4], AI
2	IOH	I	P0[5]					Al Po[1] = 4 7] = 5		45 P0[2], AI
3	IOH	I	P0[3]				XT	ALOUT, P2I	51= 6		44 P0[0], AI 43 P2[6], AI
4	IOH	I	P0[1]				Х	TALIN, P2[3 AI, P2[1	7		42 P2[4], AI
5	I/O	I	P2[7]						C = 9		41 P2[2], AI 40 P2[0], AI
6	I/O	I	P2[5]	XTAL Out					C ■ 10 3]■ 11		39 P3[6], AI
7	I/O	I	P2[3]	XTAL In					41 40	SOP	38 P3[4], AI 37 P3[2], AI
8	I/O	I	P2[1]						C = 13 7]= 14	JOF	36 P3[0], AI 35 XRES
9			NC	No connection					7] = 14 5] = 15		35 NC
10			NC	No connection				AI, P3[3]= 16		33 - NC
11	I/O	I	P4[3]						1]■ 17 C ■ 18		32 NC 31 NC
12	I/O	I	P4[1]			100	2001	N	C 🗖 19		30 NC
13			NC	No connection		I2C S	DA, SP	SPI SS, P1['I MISO, P1[7] 2 0 5] 2 1		29 NC 28 P1[6], AI
14	I/O	I	P3[7]				5	PI CLK, P1	31= 22		27 P1[4], EXT CLK
15	I/O	I	P3[5]		TC CL	K, 12C S	SCL, SP	NOSI, P1[VS	1]■ 23 S■ 24		26 P1[2], AI 25 P1[0], TC DATA, I2C SDA, SPI CLK
16	I/O	I	P3[3]								20
17	I/O	I	P3[1]								
18			NC	No connection							
19			NC	No connection							
20	IOHR	I	P1[7]	I2C SCL, SPI SS							
21	IOHR	I	P1[5]	I2C SDA, SPI MISO							
22	IOHR	I	P1[3]	SPI CLK							
23	IOHR	I	P1[1]	TC CLK ^[1] , I2C SCL, SPI MOSI							
24			VSS	Ground Pin							
25	IOHR	I	P1[0]	TC DATA ^[1] , I2C SDA, SPI CLK							
26	IOHR	I	P1[2]								
27	IOHR	I	P1[4]	EXT CLK							
28	IOHR	I	P1[6]								
29			NC	No connection							
30			NC	No connection							
31			NC	No connection							
32			NC	No connection	Pin No.	Digital	Analog	Name			Description
33			NC	No connection	41	I/O	I	P2[2]			
34			NC	No connection	42	I/O	I	P2[4]			
35			XRES	Active high external reset with internal pull down	43	I/O	I	P2[6]			
36	I/O	I	P3[0]		44	IOH	I	P0[0]			
37	I/O	1	P3[2]		45	IOH	I	P0[2]			
38	I/O	1	P3[4]		46	IOH	I	P0[4]			
39	I/O	I	P3[6]		47	IOH	I	P0[6]			
40	I/O	I	P2[0]		48	Powe	er	Vdd	Power Pin		

 $\textbf{LEGEND} \ \ A = Analog, \ I = Input, \ O = Output, \ NC = No \ Connection, \ H = 5 \ mA \ High \ Output \ Drive, \ R = Regulated \ Output \ Option.$

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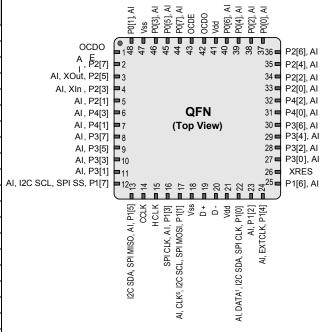
48-Pin QFN OCD

The 48-pin QFN part is for the CY8C20066 On-Chip Debug (OCD) PSoC device. Note that this part is only used for in-circuit debugging. $^{[4]}$

Table 10. Pin Definitions - CY8C20066 PSoC Device [2, 3]

Pin No.	Digital	Analog	Name	Description
1			OCDOE	OCD mode direction pin
2	I/O	ı	P2[7]	
3	I/O	ı	P2[5]	Crystal output (XOut)
4	I/O	ı	P2[3]	Crystal input (XIn)
5	I/O	ı	P2[1]	
6	I/O	ı	P4[3]	
7	I/O	ı	P4[1]	
8	I/O	ı	P3[7]	
9	I/O		P3[5]	
10	I/O		P3[3]	
11	I/O		P3[1]	
12	IOHR		P1[7]	I2C SCL, SPI SS
13	IOHR		P1[5]	I2C SDA, SPI MISO
14			CCLK	OCD CPU clock output
15			HCLK	OCD high speed clock output
16	IOHR	ı	P1[3]	SPI CLK.
17	IOHR		P1[1]	ISSP CLK ^[1] , I2C SCL, SPI MOSI
18	Pow	er	Vss	Ground connection
19	I/O		D+	USB D+
20	I/O		D-	USB D-
21	Pow	er	Vdd	Supply voltage
22	IOHR	I	P1[0]	ISSP DATA ⁽¹⁾ , I2C SDA, SPI CLK
23	IOHR	ı	P1[2]	

Figure 9. CY8C20066 PSoC Device



22	IOHR	ı	P1[0]	ISSP DATA ⁽¹⁾ , I2C SDA, SPI CLK					
23	IOHR	I	P1[2]		Pin No.	Digital	Analog	Name	Description
24	IOHR	I	P1[4]	Optional external clock input (EXTCLK)	37	IOH	I	P0[0]	
25	IOHR	I	P1[6]		38	IOH	- 1	P0[2]	
26	Inpu	ut	XRES	Active high external reset with internal pull down	39	IOH	IOH I F		
27	I/O	ı	P3[0]		40	IOH	I	P0[6]	
28	I/O	I	P3[2]		41	Pow	er	Vdd	Supply voltage
29	I/O	I	P3[4]		42			OCDO	OCD even data I/O
30	I/O	I	P3[6]		43			OCDE	OCD odd data output
31	I/O	I	P4[0]		44	IOH	I	P0[7]	
32	I/O	ı	P4[2]		45	IOH	I	P0[5]	
33	I/O	ı	P2[0]		46	IOH	I	P0[3]	Integrating input
34	I/O	ı	P2[2]		47	Power Vss		Vss	Ground connection
35	I/O	I	P2[4]		48	IOH	I	P0[1]	
36	I/O	I	P2[6]		CP	Pow	er	Vss	Center pad must be connected to ground

LEGEND A = Analog, I = Input, O = Output, NC = No Connection H = 5 mA High Output Drive, R = Regulated Output.

Note

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^{4.} This part is available in limited quantities for In-Circuit Debugging during prototype development. It is not available in production volumes.



Electrical Specifications

This section presents the DC and AC electrical specifications of the CY8C20x36/46/66/96 PSoC devices. For the latest electrical specifications, confirm that you have the most recent data sheet by visiting the web at http://www.cypress.com/psoc.

Figure 10. Voltage versus CPU Frequency

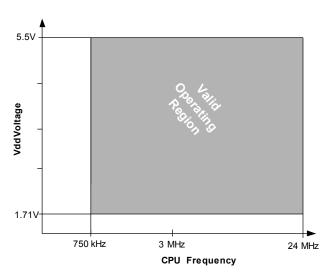
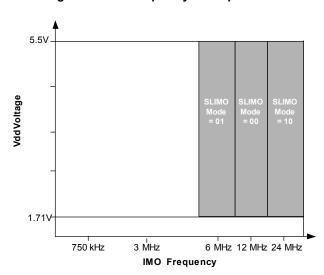


Figure 11. IMO Frequency Trim Options



The following table lists the units of measure that are used in this section.

Table 11. Units of Measure

Symbol	Unit of Measure	Symbol	Unit of Measure
°C	degree Celsius	mA	milli-ampere
dB	decibels	ms	milli-second
fF	femto farad	mV	milli-volts
Hz	hertz	nA	nanoampere
KB	1024 bytes	ns	nanosecond
Kbit	1024 bits	nV	nanovolts
kHz	kilohertz	Ω	ohm
ksps	kilo samples per second	pA	picoampere
kΩ	kilohm	pF	picofarad
MHz	megahertz	рр	peak-to-peak
MΩ	megaohm	ppm	parts per million
μΑ	microampere	ps	picosecond
μF	microfarad	sps	samples per second
μН	microhenry	s	sigma: one standard deviation
μS	microsecond	V	volts
μW	microwatts		



DC Chip-Level Specifications

The following table lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 14. DC Chip-Level Specifications

Symbol	Description	Conditions	Min	Тур	Max	Units
Vdd	Supply Voltage	Refer the table DC POR and LVD Specifications on page 24	1.71	_	5.5	V
I _{DD24}	Supply Current, IMO = 24 MHz	Conditions are Vdd = 3.0V, T _A = 25°C, CPU = 24 MHz. CapSense running at 12 MHz, no I/O sourcing current	-	2.88	4.0	mA
I _{DD12}	Supply Current, IMO = 12 MHz	Conditions are Vdd = 3.0V, T _A = 25°C, CPU = 12 MHz. CapSense running at 12 MHz, no I/O sourcing current	-	1.71	2.6	mA
I _{DD6}	Supply Current, IMO = 6 MHz	Conditions are Vdd = 3.0V, T _A = 25°C, CPU = 6 MHz. CapSense running at 6 MHz, no I/O sourcing current	-	1.16	1.8	mA
I _{SB0}	Deep Sleep Current	Vdd = $3.0V$, $T_A = 25$ °C, I/O regulator turned off	_	0.1	_	μА
I _{SB1}	Standby Current with POR, LVD and Sleep Timer	Vdd = 3.0V, T_A = 25°C, I/O regulator turned off	1	1.07	1.5	μА

DC General Purpose IO Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 3.0V to 5.5V and $-40^{\circ}\text{C} \leq T_{A} \leq 85^{\circ}\text{C}$, 2.4V to 3.0V and $-40^{\circ}\text{C} \leq T_{A} \leq 85^{\circ}\text{C}$, or 1.71V to 2.4V and $-40^{\circ}\text{C} \leq T_{A} \leq 85^{\circ}\text{C}$, respectively. Typical parameters apply to 5V and 3.3V at 25°C and are for design guidance only.

Table 15. 3.0V to 5.5V DC GPIO Specifications

Symbol	Description	Conditions	Min	Тур	Max	Units
R _{PU}	Pull up Resistor		4	5.6	8	kΩ
V _{OH1}	High Output Voltage Port 2 or 3 Pins	IOH \leq 10 μ A, maximum of 10 mA source current in all IOs	Vdd - 0.2	-	_	V
V _{OH2}	High Output Voltage Port 2 or 3 Pins	IOH = 1 mA, maximum of 20 mA source current in all IOs	Vdd - 0.9	_	_	V
V _{OH3}	High Output Voltage Port 0 or 1 Pins with LDO Regulator Disabled for Port 1	IOH < 10 μ A, maximum of 10 mA source current in all IOs	Vdd - 0.2	_	_	V
V _{OH4}	High Output Voltage Port 0 or 1 Pins with LDO Regulator Disabled for Port 1	IOH = 5 mA, maximum of 20 mA source current in all IOs	Vdd - 0.9	_	_	V
V _{OH5}	High Output Voltage Port 1 Pins with LDO Regulator Enabled for 3V Out	IOH < 10 μ A, Vdd > 3.1V, maximum of 4 IOs all sourcing 5 mA	2.85	3.00	3.3	V
V _{OH6}	High Output Voltage Port 1 Pins with LDO Regulator Enabled for 3V Out	IOH = 5 mA, Vdd > 3.1V, maximum of 20 mA source current in all IOs	2.20	_	_	V
V _{OH7}	High Output Voltage Port 1 Pins with LDO Enabled for 2.5V Out	IOH < 10 μA, Vdd > 2.7V, maximum of 20 mA source current in all IOs	2.35	2.50	2.75	V
V _{OH8}	High Output Voltage Port 1 Pins with LDO Enabled for 2.5V Out	IOH = 2 mA, Vdd > 2.7V, maximum of 20 mA source current in all IOs	1.90	_	_	V
V _{OH9}	High Output Voltage Port 1 Pins with LDO Enabled for 1.8V Out	IOH < 10 μA, Vdd > 2.7V, maximum of 20 mA source current in all IOs	1.60	1.80	2.1	V

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Table 15. 3.0V to 5.5V DC GPIO Specifications (continued)

Symbol	Description	Conditions	Min	Тур	Max	Units
V _{OH10}	High Output Voltage Port 1 Pins with LDO Enabled for 1.8V Out	IOH = 1 mA, Vdd > 2.7V, maximum of 20 mA source current in all IOs	1.20	_	-	V
V _{OL}	Low Output Voltage	IOL = 25 mA, Vdd > 3.3V, maximum of 60 mA sink current on even port pins (for example, P0[2] and P1[4]) and 60 mA sink current on odd port pins (for example, P0[3] and P1[5])	-	-	0.75	V
V _{IL}	Input Low Voltage		_	_	0.80	V
V _{IH}	Input High Voltage		2.00	_		V
V _H	Input Hysteresis Voltage		_	80	_	mV
I _{IL}	Input Leakage (Absolute Value)		_	0.001	1	μА
C _{PIN}	Pin Capacitance	Package and pin dependent Temp = 25°C	0.5	1.7	5	pF



Comparator User Module Electrical Specifications

The following table lists the guaranteed maximum and minimum specifications. Unless stated otherwise, the specifications are for the entire device voltage and temperature operating range: $-40^{\circ}\text{C} \le 7.71 = 1$

Table 21. Comparator User Module Electrical Specifications

Symbol	Description	Conditions	Min	Тур	Max	Units
T _{COMP}	Comparator Response Time	50 mV overdrive		70	100	ns
Offset				2.5	30	mV
Current		Average DC current, 50 mV overdrive		20	80	μA
PSRR	Supply voltage >2V	Power Supply Rejection Ratio		80		dB
FORK	Supply voltage <2V	Power Supply Rejection Ratio		40		dB
Input Range			0		1.5	V

ADC Electrical Specifications

Table 22. ADC User Module Electrical Specifications

Symbol	Description	Conditions Min		Тур	Max	Units
Input		•			•	•
V _{IN}	Input Voltage Range	This gives 72% of maximum Vs			1.3	V
C _{IN}	Input Capacitance				5	pF
RES	Resolution	Settings 8, 9, or 10	8		10	Bits
S8	8-Bit Sample Rate	Data Clock set to 6 MHz. Sample Rate = 0.001/ (2^Resolution/Data clock)		23.4375		ksps
S10	10-Bit Sample Rate	Data Clock set to 6 MHz. Sample Rate = 0.001/ (2^Resolution/Data clock)		5.859		ksps
DC Accur	acy	·				
DNL ^[5]	Differential Nonlinearity	fferential Nonlinearity For any configuration -1			+2	LSB
INL	Integral Nonlinearity	For any configuration	-2		+2	LSB
Eoffset	Offset Error		0	15	90	mV
I _{ADC}	Operating Current			275	350	μА
F _{CLK}	Data Clock	Source is chip's internal main oscillator. See device data sheet for accuracy.	2.25		12	MHz
PSRR	Power Supply Rejection Ration		1	•	•	
	PSRR (Vdd>3.0V)			24	dB	
	PSRR (2.2 < Vdd < 3.0)			30	dB	
	PSRR (2.0 < Vdd < 2.2)			12	dB	
	PSRR (Vdd < 2.0)			0	dB	
Egain	Gain Error	For any resolution	1		5	%FSR
R _{IN}	Input Resistance	Equivalent switched cap input resistance for 8-, 9-, or 10-bit resolution.	1/(500fF* Data-Clock)	1/(400fF* Data-Clock)	1/(300fF* Data-Clock)	Ω

Note

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^{5.} Monotonicity is not guaranteed.



AC General Purpose IO Specifications

The following table lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 26. AC GPIO Specifications

Symbol	Description	Conditions	Min	Тур	Max	Units
F _{GPIO}	GPIO Operating Frequency	Normal Strong Mode Port 0, 1	0	_	6 MHz for 1.71V <vdd<2.4v< td=""><td>MHz</td></vdd<2.4v<>	MHz
			0	_	12 MHz for 2.4V <vdd<5.5v< td=""><td></td></vdd<5.5v<>	
TRise23	Rise Time, Strong Mode, Cload = 50 pF Ports 2 or 3	Vdd = 3.0 to 3.6V, 10% – 90%	15	_	80	ns
TRise23L	Rise Time, Strong Mode Low Supply, Cload = 50 pF, Ports 2 or 3	Vdd = 1.71 to 3.0V, 10% – 90%	15	-	80	ns
TRise01	Rise Time, Strong Mode, Cload = 50 pF Ports 0 or 1	Vdd = 3.0 to 3.6V, 10% – 90% LDO enabled or disabled	10	_	50	ns
TRise01L	Rise Time, Strong Mode Low Supply, Cload = 50 pF, Ports 0 or 1	Vdd = 1.71 to 3.0V, 10% – 90% LDO enabled or disabled	10	_	80	ns
TFall	Fall Time, Strong Mode, Cload = 50 pF All Ports	Vdd = 3.0 to 3.6V, 10% – 90%	10	_	50	ns
TFallL	Fall Time, Strong Mode Low Supply, Cload = 50 pF, All Ports	Vdd = 1.71 to 3.0V, 10% – 90%	10	_	70	ns

Figure 12. GPIO Timing Diagram

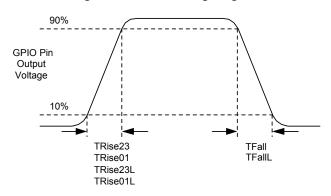




Table 34. SPI Master AC Specifications

Symbol	Description	Conditions	Min	Тур	Max	Units
F _{SCLK}	SCLK clock frequency	$\begin{array}{c} V_{DD} \geq 2.4V \\ V_{DD} < 2.4V \end{array}$			6 3	MHz
DC	SCLK duty cycle			50		%
T _{SETUP}	MISO to SCLK setup time	$\begin{array}{c} V_{DD} \geq 2.4V \\ V_{DD} < 2.4V \end{array}$	60 100			ns
T _{HOLD}	SCLK to MISO hold time		40			ns
T _{OUT_VAL}	SCLK to MOSI valid time				40	ns
T _{OUT_HIGH}	MOSI high time		40			ns

Table 35. SPI Slave AC Specifications

Symbol	Description	Conditions	Min	Тур	Max	Units
F _{SCLK}	SCLK clock frequency	$\begin{array}{c} V_{DD} \geq 2.4V \\ V_{DD} < 2.4V \end{array}$			12 6	MHz
T _{LOW}	SCLK low time		41.67			ns
T _{HIGH}	SCLK high time		41.67			ns
T _{SETUP}	MOSI to SCLK setup time		30			ns
T _{HOLD}	SCLK to MOSI hold time		50			ns
T _{SS_MISO}	SS high to MISO valid				153	ns
T _{SCLK_MISO}	SCLK to MISO valid				125	ns
T _{SS_HIGH}	SS high time				50	ns
T _{SS_CLK}	Time from SS low to first SCLK		2/SCLK			ns
T _{CLK_SS}	Time from last SCLK to SS high		2/SCLK			ns

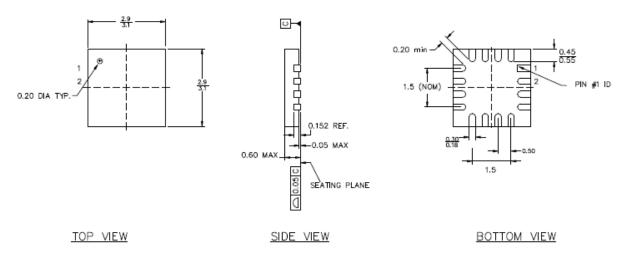


Packaging Information

This section illustrates the packaging specifications for the CY8C20x36/46/66/96 PSoC device, along with the thermal impedances for each package.

Important Note Emulation tools may require a larger area on the target PCB than the chip's footprint. For a detailed description of the emulation tools' dimensions, refer to the document titled *PSoC Emulator Pod Dimensions* at http://www.cypress.com/design/MR10161.

Figure 15. 16-pin QFN No E-pad 3x3mm Package Outline (Sawn)



PART NO.	DESCRIPTION
LG16A	LEAD-FREE
LD16A	STANDARD

NOTES:

- 1. JEDEC # MD-220
- 2. Package Weight: 0.014g
- 3, DIMENSIONS IN MM, MIN MAX

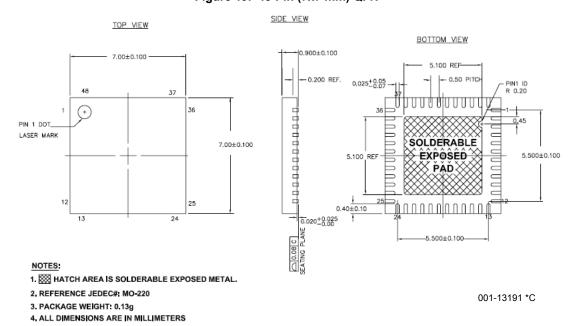
001-09116 *D



(+)0.395 0.420 0.292 0.299 **DIMENSIONS IN INCHES MIN.** MAX. 0.620 0.630 0.005 0.010 SEATING PLANE 0.088 0.092 0.095 0.110 GAUGE PLANE 0.024 0.040 ○ 0.004 0.025 BSC 0.008 0.0135

Figure 18. 48-Pin (300 MIL) SSOP

Figure 19. 48-Pin (7x7 mm) QFN



Important Notes

- For information on the preferred dimensions for mounting QFN packages, see the following Application Note at http://www.amkor.com/products/notes_papers/MLFAppNote.pdf.
- Pinned vias for thermal conduction are not required for the low power PSoC device.

51-85061 *C



Thermal Impedances

Table 36. Thermal Impedances per Package

Package	Typical θ _{JA} ^[12]
16 QFN	32.69°C/W
24 QFN ^[13]	20.90°C/W
32 QFN ^[13]	19.51°C/W
48 SSOP	69°C/W
48 QFN ^[13]	17.68°C/W

Solder Reflow Peak Temperature

This table lists the minimum solder reflow peak temperature to achieve good solderability.

Table 37. Solder Reflow Peak Temperature

Package	Minimum Peak Temperature ^[14]	Maximum Peak Temperature
16 QFN	240°C	260°C
24 QFN	240°C	260°C
32 QFN	240°C	260°C
48 SSOP	220°C	260°C
48 QFN	240°C	260°C

Notes
 12. T_J = T_A + Power x θ_{JA}.
 13. To achieve the thermal impedance specified for the QFN package, the center thermal pad must be soldered to the PCB ground plane.
 14. Higher temperatures may be required based on the solder melting point. Typical temperatures for solder are 220 ± 5°C with Sn-Pb or 245 ± 5°C with Sn-Ag-Cu paste. Refer to the solder manufacturer specifications.



Device Programmers

All device programmers are purchased from the Cypress Online Store.

CY3216 Modular Programmer

The CY3216 Modular Programmer kit features a modular programmer and the MiniProg1 programming unit. The modular programmer includes three programming module cards and supports multiple Cypress products. The kit includes:

- Modular Programmer Base
- Three Programming Module Cards
- MiniProg Programming Unit
- PSoC Designer Software CD
- Getting Started Guide
- USB 2.0 Cable

CY3207ISSP In-System Serial Programmer (ISSP)

The CY3207ISSP is a production programmer. It includes protection circuitry and an industrial case that is more robust than the MiniProg in a production programming environment. Note that CY3207ISSP needs special software and is not compatible with PSoC Programmer. The kit includes:

- CY3207 Programmer Unit
- PSoC ISSP Software CD
- 110 ~ 240V Power Supply, Euro-Plug Adapter
- USB 2.0 Cable

Accessories (Emulation and Programming)

Table 38. Emulation and Programming Accessories

Part Number	Pin Package	Flex-Pod Kit ^[15]	Foot Kit ^[16]	Adapter ^[17]
CY8C20236-24LKXI	16 QFN	CY3250-20266QFN	CY3250-16QFN-RK	See note 15
CY8C20246-24LKXI	16 QFN	CY3250-20266QFN	CY3250-16QFN-FK	See note 17
CY8C20336-24LQXI	24 QFN	CY3250-20366QFN	CY3250-24QFN-FK	See note 15
CY8C20346-24LQXI	24 QFN	CY3250-20366QFN	CY3250-24QFN-FK	See note 17
CY8C20396-24LQXI	24 QFN		Not Available	
CY8C20436-24LQXI	32 QFN	CY3250-20466QFN	CY3250-32QFN-RK	See note 15
CY8C20446-24LQXI	32 QFN	CY3250-20466QFN	CY3250-32QFN-FK	See note 17
CY8C20466-24LQXI	32 QFN	CY3250-20466QFN	CY3250-32QFN-FK	See note 17
CY8C20496-24LQXI	32 QFN		Not Available	<u>. </u>
CY8C20536-24PVXI	48 SSOP	CY3250-20X66	CY3250-48SSOP-FK	See note 17
CY8C20546-24PVXI	48 SSOP	CY3250-20X66	CY3250-48SSOP-FK	See note 17
CY8C20566-24PVXI	48 SSOP	CY3250-20X66	CY3250-48SSOP-FK	See note 17
CY8C20636-24LTXI	48 QFN	CY3250-20666QFN	CY3250-48QFN-FK	See note 17
CY8C20646-24LTXI	48 QFN	CY3250-20666QFN	CY3250-48QFN-FK	See note 17
CY8C20666-24LTXI	48 QFN	CY3250-20666QFN	CY3250-48QFN-FK	See note 17

Third-Party Tools

Several tools have been specially designed by the following third-party vendors to accompany PSoC devices during development and production. Specific details for each of these tools can be found at http://www.cypress.com under Documentation > Evaluation Boards.

Build a PSoC Emulator into Your Board

For details on how to emulate your circuit before going to volume production using an on-chip debug (OCD) non-production PSoC device, refer Application Note "Debugging - Build a PSoC Emulator into Your Board - AN2323" at http://www.cypress.com/?rID2748.

Notes

- 15. Flex-Pod kit includes a practice flex-pod and a practice PCB, in addition to two flex-pods.
- 16. Foot kit includes surface mount feet that can be soldered to the target PCB.
- 17. Programming adapter converts non-DIP package to DIP footprint. Specific details and ordering information for each of the adapters can be found at http://www.emulation.com.



Ordering Information

The following table lists the CY8C20x36/46/66/96 PSoC devices' key package features and ordering codes.

Table 39. PSoC Device Key Features and Ordering Information

Package	Ordering Code	Flash (Bytes)	SRAM (Bytes)	CapSense Blocks	Digital I/O Pins	Analog Inputs ^[18]	XRES Pin	USB
16-Pin (3x3x0.6mm) QFN	CY8C20236-24LKXI	8K	1K	1	13	13	Yes	No
16-Pin (3x3x0.6mm) QFN (Tape and Reel)	CY8C20236-24LKXIT	8K	1K	1	13	13	Yes	No
16 Pin (3x3 x 0.6 mm) QFN	CY8C20246-24LKXI	16K	2K	1	13	13	Yes	No
16 Pin (3x3 x 0.6 mm) QFN (Tape and Reel)	CY8C20246-24LKXIT	16K	2K	1	13	13	Yes	No
24-Pin (4x4x0.6mm) QFN	CY8C20336-24LQXI	8K	1K	1	20	20	Yes	No
24-Pin (4x4x0.6mm) QFN (Tape and Reel)	CY8C20336-24LQXIT	8K	1K	1	20	20	Yes	No
24 Pin (4x4 x 0.6 mm) QFN	CY8C20346-24LQXI	16K	2K	1	20	20	Yes	No
24 Pin (4x4 x 0.6 mm) QFN (Tape and Reel)	CY8C20346-24LQXIT	16K	2K	1	20	20	Yes	No
24-Pin (4x4x0.6mm) QFN	CY8C20396-24LQXI	16K	2K	1	19	19	Yes	Yes
24-Pin (4x4x0.6mm) QFN (Tape and Reel)	CY8C20396-24LQXIT	16K	2K	1	19	19	Yes	Yes
32-Pin (5x5x0.6mm) QFN	CY8C20436-24LQXI	8K	1K	1	28	28	Yes	No
32-Pin (5x5x0.6mm) QFN (Tape and Reel)	CY8C20436-24LQXIT	8K	1K	1	28	28	Yes	No
32 Pin (5x5 x 0.6 mm) QFN	CY8C20446-24LQXI	16K	2K	1	28	28	Yes	No
32 Pin (5x5 x 0.6 mm) QFN (Tape and Reel)	CY8C20446-24LQXIT	16K	2K	1	28	28	Yes	No
32 Pin (5x5 x 0.6 mm) QFN	CY8C20466-24LQXI	32K	2K	1	28	28	Yes	No
32 Pin (5x5 x 0.6 mm) QFN (Tape and Reel)	CY8C20466-24LQXIT	32K	2K	1	28	28	Yes	No
32 Pin (5x5 x 0.6 mm) QFN	CY8C20496-24LQXI	16K	2K	1	25	25	Yes	No
32 Pin (5x5 x 0.6 mm) QFN (Tape and Reel)	CY8C20496-24LQXIT	16K	2K	1	25	25	Yes	No
48-Pin SSOP	CY8C20536-24PVXI	8K	1K	1	36	36	Yes	No
48-Pin SSOP (Tape and Reel)	CY8C20536-24PVXIT	8K	1K	1	36	36	Yes	No
48-Pin SSOP	CY8C20546-24PVXI	16K	2K	1	36	36	Yes	No
48-Pin SSOP (Tape and Reel)	CY8C20546-24PVXIT	16K	2K	1	36	36	Yes	No
48-Pin SSOP	CY8C20566-24PVXI	32K	2K	1	36	36	Yes	No
48-Pin SSOP (Tape and Reel)	CY8C20566-24PVXIT	32K	2K	1	36	36	Yes	No
48 Pin (7x7 mm) QFN	CY8C20636-24LTXI	8K	1K	1	36	36	Yes	No
48 Pin (7x7 mm) QFN (Tape and Reel)	CY8C20636-24LTXIT	8K	1K	1	36	36	Yes	No
48 Pin (7x7 mm) QFN	CY8C20646-24LTXI	16K	2K	1	36	36	Yes	Yes
48 Pin (7x7 mm) QFN (Tape and Reel)	CY8C20646-24LTXIT	16K	2K	1	36	36	Yes	Yes
48 Pin (7x7 mm) QFN	CY8C20666-24LTXI	32K	2K	1	36	36	Yes	Yes
48 Pin (7x7 mm) QFN (Tape and Reel)	CY8C20666-24LTXIT	32K	2K	1	36	36	Yes	Yes
48 Pin (7x7 mm) QFN (OCD) ^[4]	CY8C20066-24LTXI	32K	2K	1	36	36	Yes	Yes

Notes

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^{18.} Dual-function Digital I/O Pins also connect to the common analog mux.



Document History Page

Revision	t Number: (ECN	Origin of Change	Submission Date	Description of Change
**	766857	HMT	See ECN	New silicon and document (Revision **).
*A	1242866	HMT	See ECN	Add features. Update all applicable sections. Update specs. Fix 24-pin QFN pinout moving pins inside. Update package revisions. Update and add to Emulation and Programming Accessories table.
*B	2174006	AESA	See ECN	Added 48-Pin SSOP Part Pinout Modified symbol R _{VDD} to R _{GND} in Table DC Analog Mux Bus Specification Added footnote in Table DC Analog Mux Bus Specification Added 16K FLASH Parts. Updated Notes, Package Diagrams and Ordering Information table. Updated Thermal Impedance and Solder Reflow tables
*C	2587518	TOF/JASM/MNU/ HMT	10/13/08	Converted from Preliminary to Final Fixed broken links. Updated data sheet template. Added operating voltage ranges with USB ADC resolution changed from 10-bit to 8-bit Included ADC specifications table Included Comparator specification table Included Voh7, Voh8, Voh9, Voh10 specs Flash data retention – condition added to Note Input leakage spec changed to 1 µA max GPIO rise time for ports 0,1 and ports 2,3 made common AC Programming specifications updated Included AC Programming cycle timing diagram AC SPI specification updated The VIH for 3.0 <vdd<2.4 1.6="" 2.0="" added="" changed="" clk="" diagrams="" f<sub="" for="" from="" impedances="" p1[0]="" package="" packages="" qfn="" specification="" spi="" thermal="" to="" updated="" usb="">GPIO parameter in Table 23 Updated voltage ranges for F_{SPIM} and F_{SPIS} in Table 30 Update Development Tools, add Designing with PSoC Designer. Edit, fix links, notes and table format. Update R_{IN} formula, fix TRise parameter names in GPIO figure, fix Switch Rate note. Update maximum data in Table 20. DC POR and LVD Specifications.</vdd<2.4>
*D	2649637	SNV/AESA	03/17/2009	Changed title to "CY8C20x36/46/66, CY8C20396 CapSense™ Applications". Updated data sheet Features, pin information, and ordering information sections. Updated package diagram 001-42168 to *C.
*E	2700196	SNV/PYRS	04/30/2009	Added part numbers CY8C20496, CY8C20536, CY8C20546, CY8C20636, CY8C20646 Updated Features on page 1 Added 48-Pin QFN without USB pin Diagram and Pin Definition table Added 32-Pin QFN (with USB) package Added SPI Master and Slave AC Specifications Updated Emulations and Programming Accessories Table on page 33 Updated Ordering Information on page 37 Removed reference to Hi-Tech C Compiler in Development Tool Selection on page 35



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